

HI-AM ^{3rd} | 2020 Conference

HOLISTIC INNOVATION IN
ADDITIVE MANUFACTURING

INVITATION TO SPONSOR

JUNE 25 & 26
MONTRÉAL, QC, CANADA

nserc-hi-am.ca/2020



What is HI-AM?

Additive manufacturing (AM) has the potential to change the entire manufacturing sector by 2030. Despite the recent developments, there are several challenges hindering the widespread industry adoption of this technology from expensive and limited metal powder feedstock to the need for increased process reliability.

The NSERC Network for Holistic Innovation in Additive Manufacturing (HI-AM) has been formed to work on innovative solutions to address these challenges and to equip Canada for the era of Industry 4.0 and “digital-to-physical conversion.” With major investment from NSERC and CFI, the Network investigates fundamental scientific

issues associated with AM pre-fabrication, fabrication, and post-fabrication processing. It facilitates collaboration between Canada’s leading research groups in advanced materials processing and characterization, powder synthesis, alloy development, advanced process simulation and modeling, precision tool-path planning, controls, sensing, and applications.

University of Waterloo is very proud to host the first strategic Canadian Network in additive manufacturing bringing together 7 universities, 13 industrial partners, various government organizations, and 10 international collaborators.



HI-AM Conference

Launched in 2018, the HI-AM conference is the only academic conference in Canada focused exclusively on metal additive manufacturing. With over 100 additive manufacturing experts and decision-makers from academia, research institutes, industry and government participating, HI-AM 2020 is an event not to be missed.

The focus of HI-AM conference is to provide a platform for the presentation of recent R&D advancements in the field of metal additive manufacturing under 4 research themes:

- 1. Material development**
- 2. Advanced process modeling**
- 3. Process monitoring and control**
- 4. Innovative AM processes/products**

Please join us in
Montréal, Canada
June 25 & 26, 2020
for the 3rd HI-AM
Conference

VENUE:

New Residence Hall
3625 Park Avenue,
McGill University
Montréal, QC H2X 3P8
Canada



We invite you to sponsor the 3rd HI-AM Conference

The HI-AM Conference will bring together principal researchers and key decision-makers of the metal additive manufacturing field from across Canada – and the world.

Sponsors will have the opportunity to:

- Build relationships with AM decision-makers from industry and academia.
- Promote their products/services to our wide network of industrial partners.
- Expand their brand outreach through support of academic and educational events.

HI-AM PREVIOUS SPONSORS



HI-AM INDUSTRIAL AND HEALTHCARE PARTNERS



HI-AM GOVERNMENT AND NON-PROFIT PARTNERS



Sponsorship Packages

Benefits

Note: all fees are in Canadian Dollars

	Silver Package \$500	Gold Package \$1,000	Platinum Package \$2,000	Conference Dinner \$3,000
Logo recognition: <ul style="list-style-type: none"> ▪ Conference website ▪ Break slides and signage ▪ Information package 	Yes	Yes	Yes	Yes
Supplying promo items for delegate bags	No	No	Yes	Yes
Location for tabletop exhibit displays	No	No	Yes	Yes
Complimentary full conference pass	-	1	2	4
Opportunity to make brief remarks during gala	No	No	No	Yes

For a custom sponsorship package, please contact Farzad Liravi at fliravi@uwaterloo.ca



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